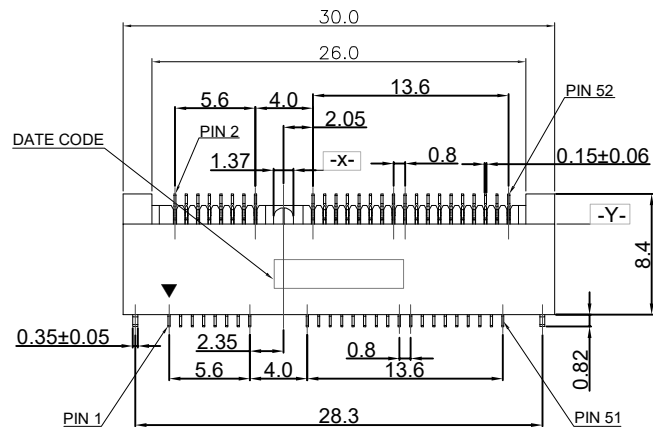
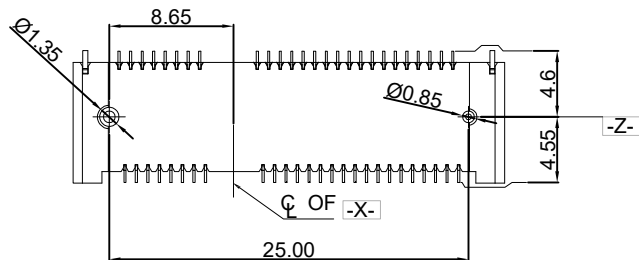
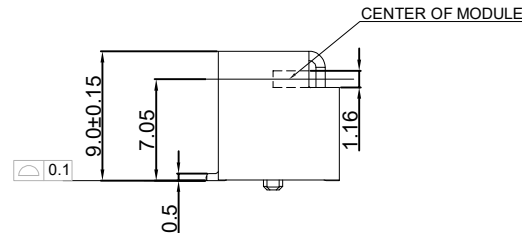
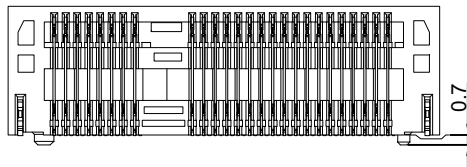


RoHS

REV	ECN NO.	DESRPTION	DESIGN	APPROVAL	DATE
A1	NEW	更换图框			2026.07.21



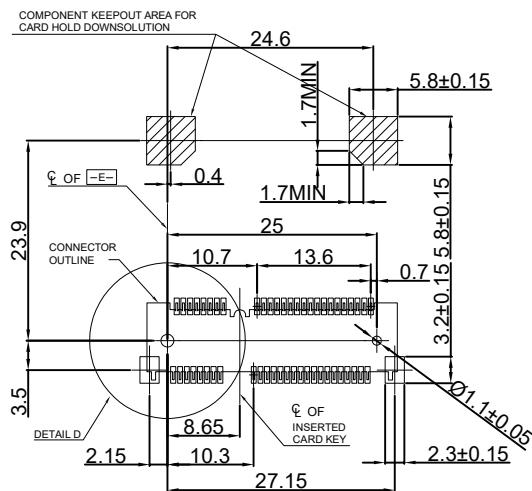
- NOTES:
- 1.MATERIAL:
HOUSING:THERMOPLASTIC,HIGH TEMP,UL94V-0,BLACK
COLOR,CONTACTS:COPPER ALLOY.PEGS:COPPER ALLOY.
 - 2.FINISH:
CONTACTS:SELECTED GOLD PLATING ON THE CONTACT AREA,1u"MIN.
GOLD PLATING ON THE SOLDER TAILS,50 u"MIN.NICKEL UNDERPLATING
OVER ALL.PEGS:120u"MIN.MATTE-TIN OVER 50u"MIN.NICKEL.
 - 3.PACKAGING:TAPE & REEL
 - 4.PRODUCT SPECIFICATION:PS-MINI PCI-E-01



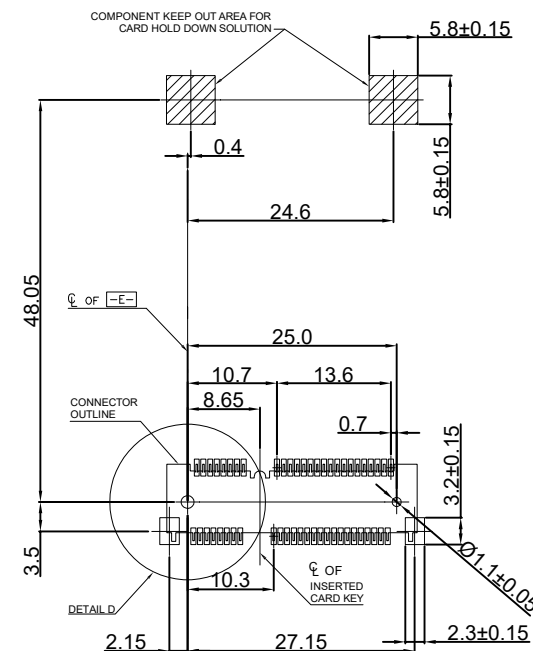
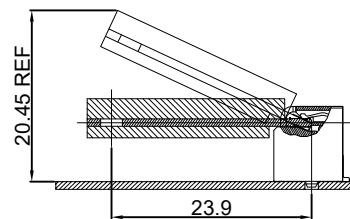
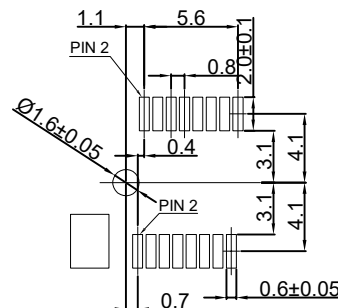
X. 0.3	X.°±	PART NO: XF-K80100174		XFCN 兴飞连接器	
. X±0.2	.X°±	TITLE: MINI PCI EAPRESS		0769-82001899	
. XX±0.08	.XX°±			www.xfconn.com	
. XXX±0.03	.XXX°±			DWG NO: /	
UNITS:	mm				
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF XFCN AND SHALL NOT BE REPRODUCED, COPIED OR CUED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF XFCN		APPD	Chen ZhiQiang		
		CHKD	Liu Wei	VIEW	
		DRAW	Chen HongJiang	SCALE	SHEET REV
		DATE	2026.07.21	NONE	1/4 A1

RoHS

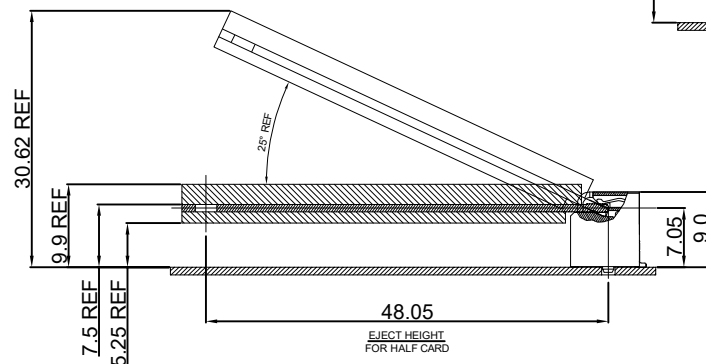
REV	ECN NO.	DESCRIPTION	DESIGN	APPROVAL	DATE
A1	NEW	更换图框			2026.07.21



IS THE TOP SURFACE OF PCB.
RECOMMENDED P.C. BOARD PATTERN LAYOUT
FOR HALF CARD CONNECTOR
(TOP VIEW)



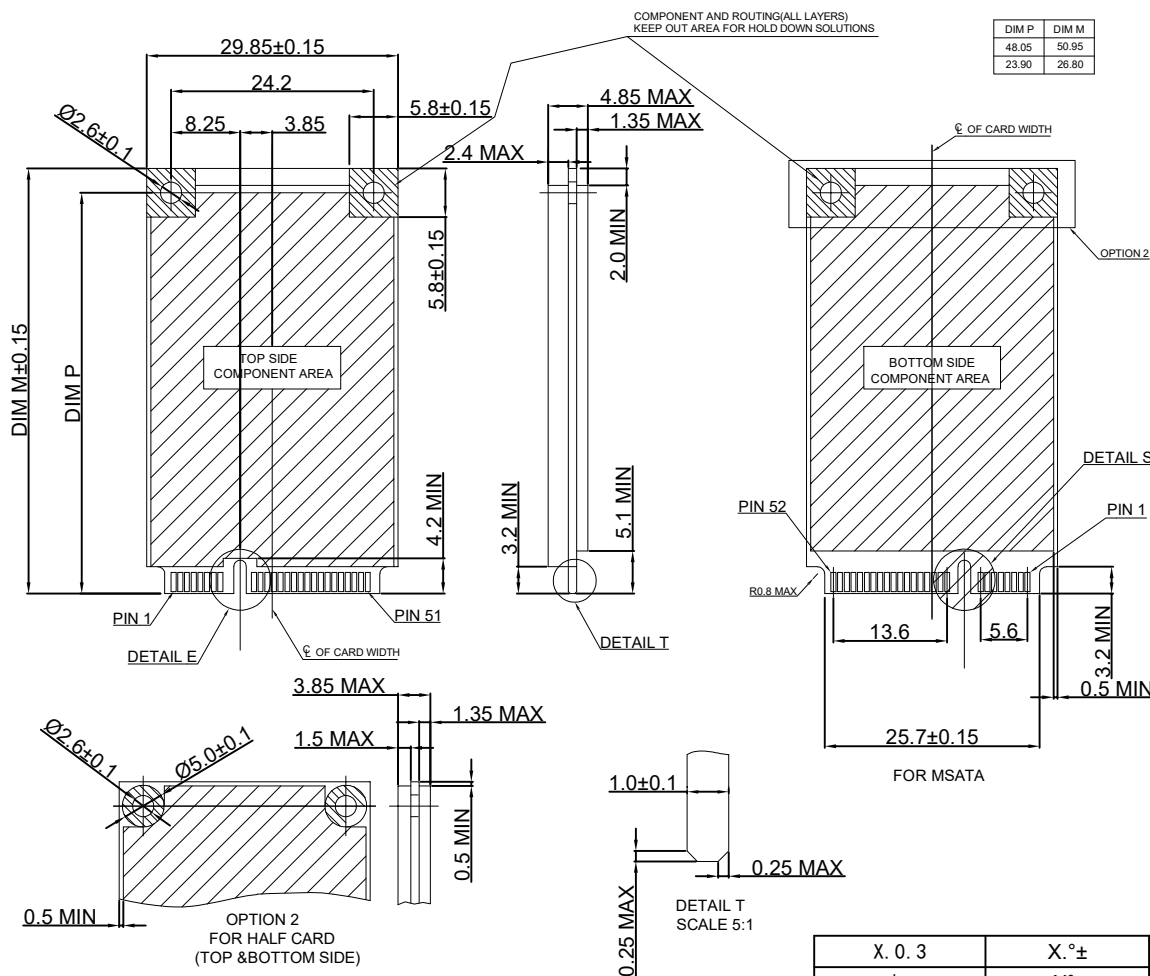
IS THE TOP SURFACE OF PCB.
RECOMMENDED P.C. BOARD PATTERN LAYOUT
FOR HALF CARD CONNECTOR
(TOP VIEW)



X. 0.3	X.°±	PART NO: XF-K80100174		XFCN 兴飞连接器	
.X±0.2	.X°±	TITLE: MINI PCI EAPRESS		0769-82001899	
.XX±0.08	.XX°±			www.xfconn.com	
.XXX±0.03	.XXX°±			DWG NO: /	
UNITS:	mm	APPD	Chen ZhiQiang		
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF XFCN AND SHALL NOT BE REPRODUCED, COPIED OR CUED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF XFCN		CHKD	Liu Wei	VIEW	⊕
		DRAW	Chen HongJiang	SCALE	SHEET
		DATE	2026.07.21	NONE	2/4
					REV A1

RoHS

REV	ECN NO.	DESCRIPTION	DESIGN	APPROVAL	DATE
A1	NEW	更换图框			2026.07.21



NOTES:
CARD THICKNESS APPLIES ACROSS TABS AND INCLUDES
PLATING AND/OR METALLIZATION.

EDGE BEVEL MUST BE PRESENT AND FREE OF CUTTING
BURRS FROM PCB AND CONTACT MATERIALS.

COMPONENT AND ROUTING(TOP/BOTTOM LAYER)KEEP
OUT AREA FOR HOLD DOWN SOLUTIONS.

X. 0. 3	X. °±	PART NO: XF-K80100174		XFCN 兴飞连接器	
. X±0. 2	. X°±	TITLE: MINI PCI EAPRESS		0769-82001899	
. XX±0. 08	. XX°±			www.xfconn.com	
. XXX±0. 03	. XXX°±			DWG NO: /	
UNITS:	mm	APPD	Chen ZhiQiang	VIEW	⊕
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF XFCN AND SHALL NOT BE REPRODUCED, COPIED OR CUED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF XFCN		CHKD	Liu Wei	SCALE	SHEET
		DRAW	Chen HongJiang	SCALE	REV
		DATE	2026.07.21	NONE	4/4
					A1